

DATE SHEET

D3K

D2KB05 ~D2KB100

2A/50-1000V

2A

2A Glass Passivated Single-Phase Bridge Rectifier

Features

Glass passivated chip

Low Reverse Leakage Current

60

High surge current capability to 60 Amperes

UL

94V-0

UL

E249161



Plastic material has Underwriters Laboratory flammability recognition 94V-0 Recognized File # E249161

ROSH

ROHS compliance



260 +5 /10

High temperature soldering guaranteed: 260 +5 /10 seconds

Mechanical Data

Case : Molded plastic case

Polarity Polarity symbols being marked on body

M3

Mounting Position : Fixing the bridge rectifier with M3screw to the heat sink. Coat silicon thermal compound between backside of the bridge,which will be contacted with the heat sink for maximizing heat transfer.

1.45

Weight : About 1.45 grams

Applications

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Household Electric Appliances air-conditioning white appliances, etc

Power supply Computer power supply,Adapter power supply,,Server power supply, etc

Industrial equipment Electric energy meter, etc

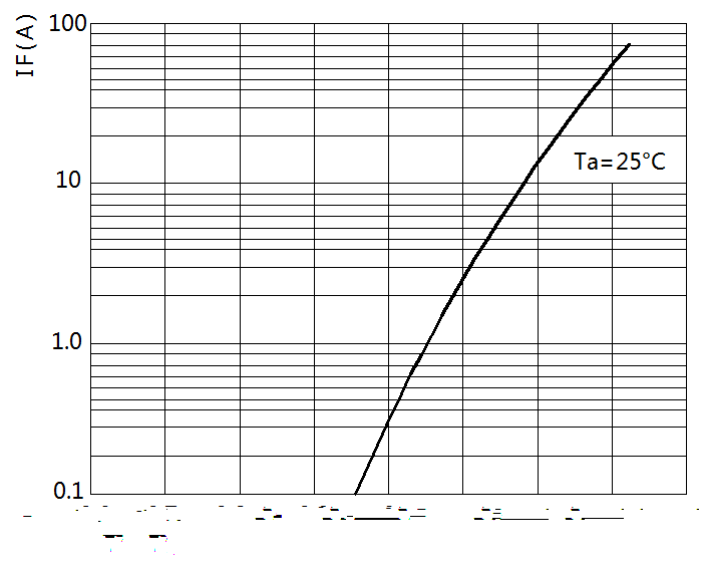
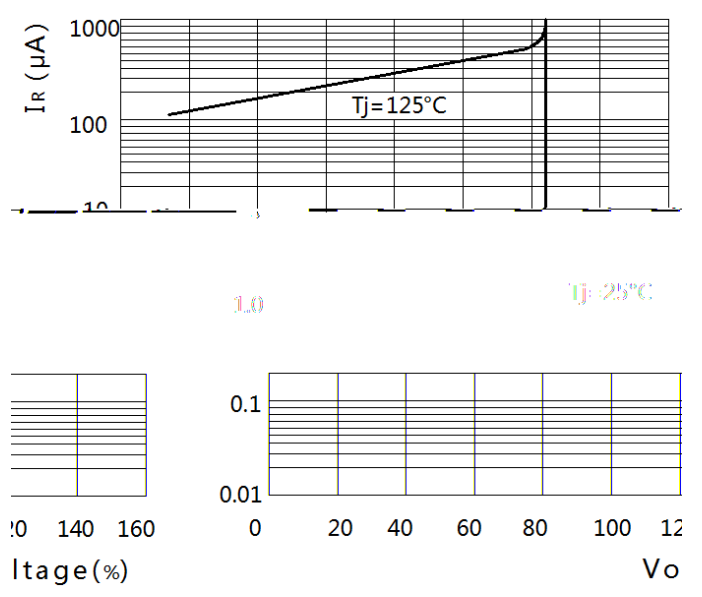
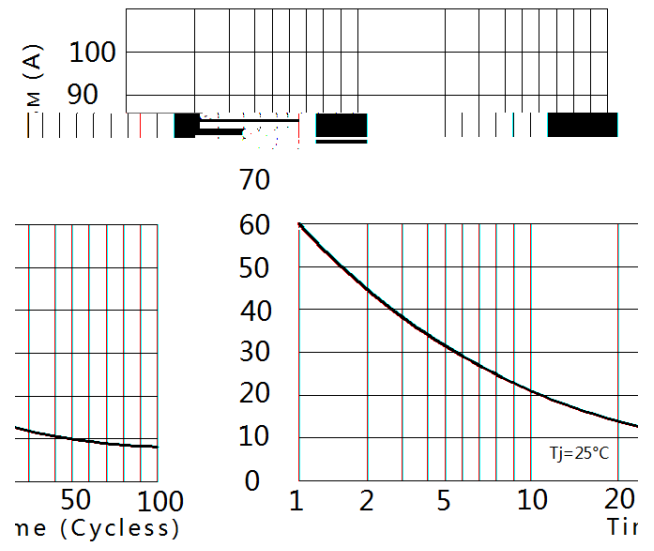
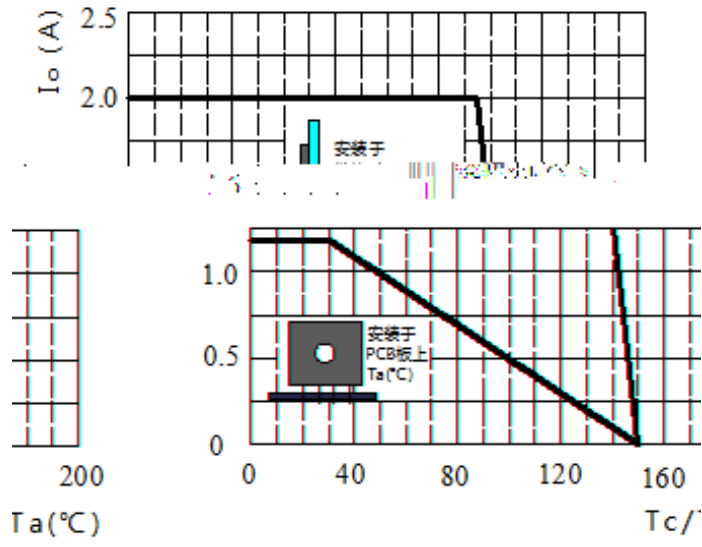
IP

Communication equipment (Adjust demodulator, Wireless router, Communication automatic control IP, etc.)

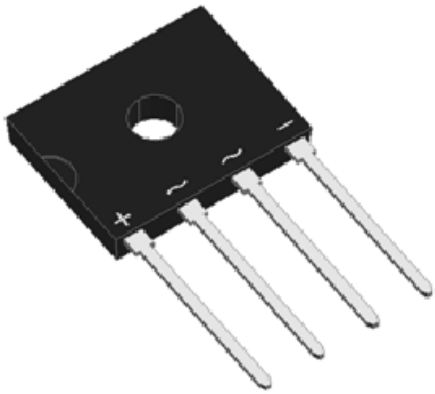
Type	VRRM	VRSM
D2KB05	50	150
D2KB10	100	200
D2KB20	200	300
D2KB40	400	500
D2KB60	600	700
D2KB80	800	900
D2KB100	1000	1100

Maximum Ratings and Thermal Characteristics @ Ta = 25 unless otherwise noted					
Item	Symbol	Conditions		Rated value	Unit
Average Rectified Output Current	Io	60Hz , 60Hz sine wave load	,Tc=135 with heatsink,Tc=135	2.0(note 2)	A
			,Ta=30 without heatsink,Ta=40	1.2 (note 1)	
Peak Surge Forward Current	IFSM	60HZ , 60HZ sine wave,1 cycle , Tj=25	tj=25	60	A
Rating for fusing	i ² t	1ms<t<8.3ms,Tj=25 1ms<t<8.3ms,Tj=25	Rating of per diode	15	A ² S
Storage Temperature	TSTG			-40 +150	
Junction Temperature	TJ				

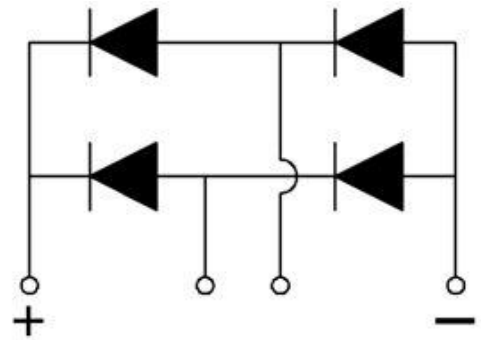
Rating Characteristic



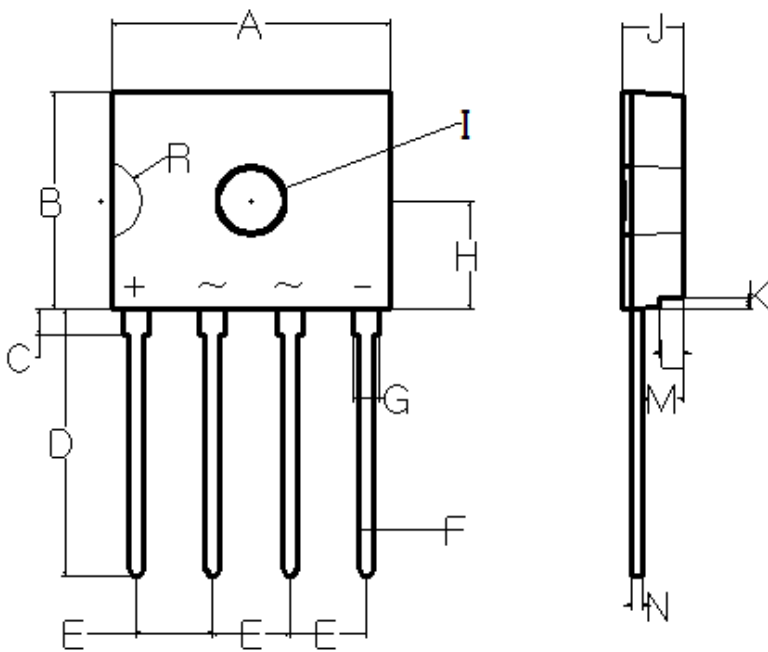
Outside view



Circuit diagram



Package Outline Dimensions

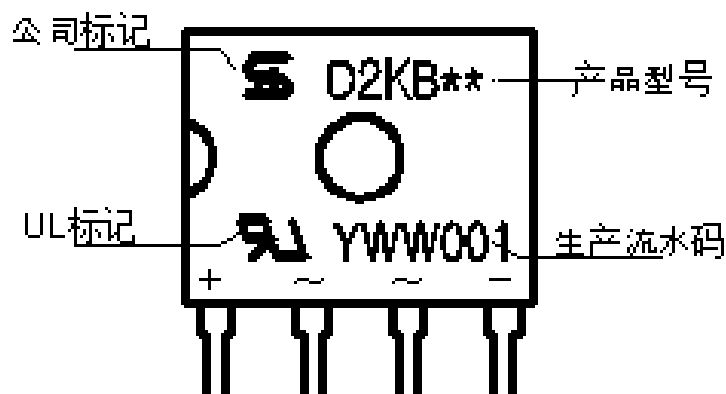


No.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	13.3	14.3	0.523	0.563
B	10.3	11.3	0.405	0.445
C	1.2	1.4	0.047	0.055
D	12.8	13.8	0.504	0.544
E	3.76	3.86	0.130	0.170
F	0.63	0.83	0.025	0.033
G	1.2	1.4	0.047	0.055
H	5.2	5.6	0.205	0.221
I	3.05	3.45	0.120	0.136
J	2.9	3.3	0.114	0.130
K	0.5	0.7	0.020	0.028
L	1.0	1.4	0.039	0.055
M	1.9	2.3	0.075	0.091
N	0.4	0.6	0.016	0.024

Bill of Materials

No.		QTY	Material
1		4	
2		1	
3		4	
4		1.2g	
5		0.02g	=90%:8%:2%

/ Component molding /Marking Diagram



1. $V_{RRM} = \frac{D \cdot K_B}{2} \cdot I_o = *1 \cdot **$
2. Y A 2009 WW 05 5 ,

Packaging and storage

1.

	5000 /	300*220*180	500 /	288*103*28
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2.

25 ±3 60 6

100 2-4h

1			1.0		2017.3.6
2	IFSM VF		2.0		2017.06.02